

The documentation and process conversion measures necessary to comply with this document shall be completed by 13 November 2019.

INCH-POUND

MIL-PRF-19500/768C
 13 July 2019
 SUPERSEDING
 MIL-PRF-19500/768B
 27 August 2014

PERFORMANCE SPECIFICATION SHEET

SEMICONDUCTOR DEVICE, DIODE, SILICON, ULTRAFAST RECOVERY, POWER RECTIFIER,
 TYPES 1N7066, 1N7067, 1N7068, AXIAL LEADED AND SURFACE MOUNT PACKAGES,
 QUALITY LEVELS JAN, JANTX, JANTXV, AND JANS

This specification is approved for use by all Departments and Agencies of the Department of Defense.

The requirements for acquiring the product described herein shall consist of this specification sheet and [MIL-PRF-19500](#).

1. SCOPE

1.1 Scope. This specification covers the performance requirements for silicon, ultra fast recovery, power rectifier diodes. Four levels of product assurance (JAN, JANTX, JANTXV and JANS) are provided for each encapsulated device type as specified in [MIL-PRF-19500](#).

1.2 Package outlines. The device package outlines are as follows: An axial leaded package in accordance with [figure 1](#) and square end-cap surface mount package (US) in accordance with [figure 2](#).

1.3 Maximum ratings. Unless otherwise specified, $T_A = +25^\circ\text{C}$.

1.3.1 Ratings applicable to all Part or Identifying Numbers (PIN). $T_{\text{STG}} = T_{\text{J(max)}} = -65^\circ\text{C}$ to $+175^\circ\text{C}$.

1.3.2 Ratings applicable to individual types.

Col. 1	Col. 2	Col. 3	Col. 4	Col. 5	Col. 6	Col. 7
Types	V_{RWM}	I_O $T_L \leq +55^\circ\text{C}$ $L = .125$ inch (3.175 mm) or $T_{\text{EC}} < +100^\circ\text{C}$ (1) (2)	I_{FSM} at $T_A = +25^\circ\text{C}$ operating at I_O $t_p = 8.3$ ms	t_{rr}	$R_{\theta\text{JL}}$ at $L = .125$ inch (3.175 mm)	$R_{\theta\text{JEC}}$
		<u>A</u>	<u>A(pk)</u>	<u>ns</u>	<u>°C/W</u>	<u>°C/W</u>
1N7066, US	100	10	350	30	8	4.5
1N7067, US	150	10	350	30	8	4.5
1N7068, US	200	10	350	30	8	4.5

(1) Axial lead, derate at 83.3 mA/°C above rated T_L .

(2) Surface mount, derate at 133.3 mA/°C above rated T_{EC} .

Comments, suggestions, or questions on this document should be addressed to DLA Land and Maritime, VAC, P.O. Box 3990, Columbus, OH 43218-3990, or emailed to Semiconductor@dla.mil. Since contact information can change, you may want to verify the currency of this address information using the ASSIST Online database at <https://assist.dla.mil>.

AMSC N/A

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